阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网,版权归原作者所有。如读者和版权方有任何异议请及时告之,我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译,其目的是协助用户阅读,该译文无法自动跟随原稿更新,同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料,来自厂商的技术支持或者使用者的心得体会等,其内容可能存在描 叙上的差异,建议读者做出适当判断。
- 4.如需与我们联系,请发邮件到marketing@iczoom.com,主题请标有"数据手册"字样。

Read Statement

- 1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
- 2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
- 3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
- 4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets" .

Low Skew, 1-to18 LVPECL-to-LVCMOS/LVTTL Fanout Buffer

DATA SHEET

General Description

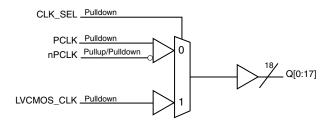
The ICS83940I-01 is a low skew, 1-to-18 LVPECL-to-LVCMOS/ LVTTL Fanout Buffer. The ICS83940I-01 has two selectable clock inputs. The PCLK, nPCLK pair can accept LVPECL or SSTL input levels. The single-ended clock input accepts LVCMOS or LVTTL input levels.

The ICS83940I-01 is characterized at full 3.3V, full 2.5V and mixed 3.3V input and 2.5V output operating supply modes. Guaranteed output and part-to-part skew characteristics make the ICS83940I-01 ideal for those clock distribution applications demanding well defined performance and repeatability.

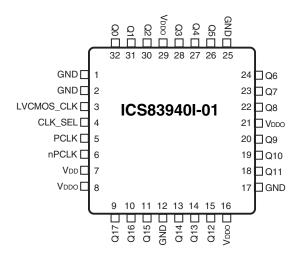
Features

- Eighteen LVCMOS/LVTTL outputs, 23Ω typical output impedance
- Selectable LVCMOS CLK or LVPECL clock inputs
- PCLK, nPCLK pair can accept the following differential input levels: LVPECL, SSTL
- LVCMOS_CLK supports the following input types: LVCMOS or LVTTL
- Maximum output frequency: 175MHz
- Additive phase jitter, RMS: 0.108ps (typical), 3.3V/3.3V
- Output skew: 115ps (maximum)
- Part-to-part skew: 800ps (maximum), 3.3V/3.3V
- Operating supply modes:
- Core/Output 3.3V/3.3V 3.3V/2.5V 2.5V/2.5V
- -40°C to 85°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

Block Diagram



Pin Assignment



32-Lead LQFP 7mm x 7mm x 1.4mm package body Y Package **Top View**

Table 1. Pin Descriptions

Number	Name	Т	уре	Description	
1, 2, 12, 17, 25	GND	Power		Power supply ground.	
3	LVCMOS_CLK	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.	
4	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects LVCMOS_CLK input. When LOW, selects PCLK, nPCLK inputs. LVCMOS / LVTTL interface levels.	
5	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.	
6	nPCLK	Input	Pullup/ Pulldown	Inverting differential LVPECT clock input V55/2 detailit when left tigat	
7	V _{DD}	Power		Power supply pin.	
8, 16, 21, 29	V_{DDO}	Power		Output supply pins.	
9, 10, 11, 13, 14, 15, 18, 19, 20, 22, 23, 24, 26, 27, 28, 30, 31, 32	Q17, Q16, Q15, Q14, Q13, Q12, Q11, Q10, Q9, Q8, Q7, Q6, Q5, Q4, Q3, Q2, Q1, Q0	Output		Single-ended clock outputs. LVCMOS/LVTTL interface levels.	

NOTE: Pullup and Pulldown refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ
R _{PULLUP}	Input Pullup Resistor			51		kΩ
C _{PD}	Power Dissipation Capacitance (per output)			9		рF
R _{OUT}	Output Impedance		17	23	28	Ω

Function Tables

Table 3A. Clock Select Function Table

Control Input	Clo	ock
CLK_SEL	PCLK, nPCLK	LVCMOS_CLK
0	Selected	De-selected
1	De-selected	Selected

Table 3B. Clock Input Function Table

		Inputs		Outputs		
CLK_SEL	LVCMOS_CLK	PCLK	nPCLK	Q[0:17]	Input to Output Mode	Polarity
0	_	0	1	LOW	Differential to Single-Ended	Non-Inverting
0	_	1	0	HIGH	Differential to Single-Ended	Non-Inverting
0	_	0	Biased; NOTE 1	LOW	Single-Ended to Single-Ended	Non-Inverting
0	_	1	Biased; NOTE 1	HIGH	Single-Ended to Single-Ended	Non-Inverting
0	_	Biased; NOTE 1	0	HIGH	Single-Ended to Single-Ended	Inverting
0	_	Biased; NOTE 1	1	LOW	Single-Ended to Single-Ended	Inverting
1	0	_	-	LOW	Single-Ended to Single-Ended	Non-Inverting
1	1	_	_	HIGH	Single-Ended to Single-Ended	Non-Inverting

NOTE 1: Please refer to the Application Information Section, Wiring the Differential Input to Accept Single-ended Levels.

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V _{DD}	3.6V
Inputs, V _I	-0.3V to V _{DD} + 0.3V
Outputs, V _O	-0.3V to V _{DDO} + 0.3V
Input Current, I _{IN}	±20mA
Package Thermal Impedance, θ_{JA}	53.5°C/W (0 mps)
Storage Temperature, T _{STG}	-40°C to 125°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = -40$ °C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Power Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Supply Voltage		3.135	3.3	3.465	V
I _{DD}	Power Supply Current				26	mA
I _{DDO}	Output Supply Current	No Load			28	mA

Table 4B. Power Supply DC Characteristics, $V_{DD} = V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Power Supply Voltage		2.375	2.5	2.625	V
V_{DDO}	Output Supply Voltage		2.375	2.5	2.625	V
I _{DD}	Power Supply Current				25	mA
I _{DDO}	Output Supply Current	No Load			26	mA

Table 4C. Power Supply DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = -40$ °C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Power Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Supply Voltage		2.375	2.5	2.625	V
I _{DD}	Power Supply Current				26	mA
I _{DDO}	Output Supply Current	No Load			26	mA

Table 4D. LVCMOS DC Characteristics, $V_{DD} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $V_{DDO} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_A = -40$ °C to 85°C to 85°C rate of the state of the st

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
\ <u>'</u>	Input High Voltage	LVCMOS_CLK	V 2.2V or 2.5V	2		Naximum V _{DD} + 0.3 1.3 0.8 150	V
V _{IH}	Input High Voltage	CLK_SEL	$V_{DD} = 3.3V \text{ or } 2.5V$	2			V
\ <u>'</u>	Input Low Voltage	LVCMOS_CLK	V _{DD} = 3.3V or 2.5V	-0.3		1.3	V
V _{IL}	Input Low Voltage	CLK_SEL	V _{DD} = 3.3V or 2.5V	-0.3		0.8	
I _{IH}	Input High Current	CLK_SEL, LVCMOS_CLK	V _{DD} = V _{IN} = 3.465V or 2.625V			150	μΑ
I _{IL}	Input Low Current	CLK_SEL, LVCMOS_CLK	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-5			μΑ
\ <u>'</u>	Output High Voltage; NOTE 1		V _{DDO} = 3.465V	2.8			V
V _{OH}			V _{DDO} = 2.625V	2.1			V
V _{OL}	Output Low Voltage;	NOTE 1	V _{DDO} = 3.465V or 2.65V			0.55	V

NOTE 1: Outputs terminated with 50Ω to $V_{DDO}/2$. See Parameter Measurement Information section, *Output Load Test Circuit diagram.*

Table 4E. LVPECL DC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = -40$ °C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I _{IH}	Input High Current	PCLK, nPCLK	$V_{DD} = V_{IN} = 3.465 V \text{ or } 2.625 V$			150	μA
	Input Low Current	PCLK	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-10			μA
¹IL	input Low Current	nPCLK	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-150			μA
I _{IN}	Input Current					±200	μA
V_{PP}	Peak-to-Peak Input V	oltage		500		1000	mV
V_{CMR}	Common Mode Input	Voltage; NOTE 1		V _{DD} – 1.4		V _{DD} – 0.6	V

NOTE 1: Common mode voltage is defined as V_{IH} .

Table 4F. LVPECL DC Characteristics, $V_{DD} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I _{IH}	Input High Current	PCLK, nPCLK	$V_{DD} = V_{IN} = 3.465 V$ or 2.625 V			150	μA
	Input Low Current	PCLK	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-10			μΑ
¹IL	Input Low Current	nPCLK	V _{DD} = 3.465V or 2.625V, V _{IN} = 0V	-150			μΑ
I _{IN}	Input Current					±200	μΑ
V _{PP}	Peak-to-Peak Input \	/oltage		300		1000	mV
V _{CMR}	Common Mode Input	Voltage; NOTE 1		V _{DD} – 1.4		V _{DD} – 0.6	V

NOTE 1: Common mode voltage is defined as V_{IH} .

AC Electrical Characteristics

Table 5A. AC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{OUT}	Output Frequency					175	MHz
	Propagation	PCLK, nPCLK; NOTE 1, 5	<i>f</i> ≤ 150MHz	1.6		3.0	ns
	Delay	LVCMOS_CLK; NOTE 2, 5	<i>f</i> ≤ 150MHz	1.8		3.0	ns
t _{PLH}	Propagation	PCLK, nPCLK; NOTE 1, 5	<i>f</i> > 150MHz	1.6		3.3	ns
	Delay	LVCMOS_CLK; NOTE 2, 5	<i>f</i> > 150MHz	1.8		3.2	ns
	Additive Phase	PCLK, nPCLK			0.145		ps
<i>t</i> jit	Jitter, RMS; Refer to Additive Phase Jitter Section	LVCMOS_CLK	155.52MHz, Integration Range: 12kHz – 20MHz		0.108	175 3.0 3.0 3.3	ps
tsk(o)	Output Skew; NOT	E 3, 5	Measured on the Rising Edge @ V _{DDO} /2			115	ps
	Part-to-Part Skew;	PCLK, nPCLK	<i>f</i> ≤ 150MHz			1.4	ns
	NOTE 6	LVCMOS_CLK	<i>f</i> ≤ 150MHz			1.2	ns
tok(nn)	Part-to-Part Skew;	PCLK/nPCLK	<i>f</i> > 150MHz			1.7	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	<i>f</i> > 150MHz			1.4	ns
	Part-to-Part Skew;	PCLK/nPCLK	Measured on the Rising Edge			975	ps
	NOTE 4, 5	LVCMOS_CLK	@ V _{DDO} /2			800	ps
t _R / t _F	Output Rise/Fall Tir	me	20% to 80%	300		800	ps
odc	Output Duty Cycle		<i>f</i> ≤ 150MHz	45		55	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE: All parameters measured at 150MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output V_{DDO}/2.

NOTE 2: Measured from V_{DD}/2 to V_{DDO}/2.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDO}/2.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage, same temperature, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{\rm DDO}/2$.

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDO}/2$.

Table 5B. AC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 2.5V \pm 5\%$, $T_A = -40$ °C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{OUT}	Output Frequency					175	MHz
^t PLH	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	<i>f</i> ≤ 150MHz	1.7		3.2	ns
		LVCMOS_CLK; NOTE 2, 5	<i>f</i> ≤ 150MHz	1.7		3.0	ns
	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	<i>f</i> > 150MHz	1.6		3.4	ns
		LVCMOS_CLK; NOTE 2, 5	<i>f</i> > 150MHz	1.8		3.3	ns
fjit	Additive Phase Jitter, RMS; Refer to Additive Phase Jitter Section	PCLK, nPCLK	155.52MHz, Integration Range: 12kHz – 20MHz		0.199		ps
		LVCMOS_CLK			0.137		ps
tsk(o)	Output Skew; NOT	E 3, 5	Measured on the Rising Edge @ V _{DDO} /2			150	ps
	Part-to-Part Skew; NOTE 6	PCLK, nPCLK	<i>f</i> ≤ 150MHz			1.5	ns
		LVCMOS_CLK	<i>f</i> ≤ 150MHz			1.3	ns
tok(nn)	Part-to-Part Skew; NOTE 6	PCLK, nPCLK	<i>f</i> > 150MHz			1.8	ns
tsk(pp)		LVCMOS_CLK	<i>f</i> > 150MHz			1.5	ns
	Part-to-Part Skew; NOTE 4, 5	PCLK, nPCLK	Measured on the Rising Edge			975	ps
		LVCMOS_CLK	@ V _{DDO} /2			875	ps
t_R / t_F	Output Rise/Fall Time		20% to 80%	300		800	ps
odc	Output Duty Cycle		<i>f</i> ≤ 150MHz	45		55	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE: All parameters measured at 150MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output V_{DDO}/2.

NOTE 2: Measured from $V_{DD}/2$ to $V_{DDO}/2$.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDO}/2.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage, same temperature, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V_{DDO}/2.

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDO}/2$.

Table 5C. AC Characteristics, $V_{DD} = V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{OUT}	Output Frequency					175	MHz
t _{PLH}	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	<i>f</i> ≤ 150MHz	1.2		3.8	ns
		LVCMOS_CLK; NOTE 2, 5	<i>f</i> ≤ 150MHz	1.5		3.2	ns
	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	<i>f</i> > 150MHz	1.5		3.7	ns
		LVCMOS_CLK; NOTE 2, 5	<i>f</i> > 150MHz	2.0		3.6	ns
	Additive Phase Jitter, RMS; Refer to Additive Phase Jitter Section	PCLK, nPCLK			0.323		ps
<i>t</i> jit		LVCMOS_CLK	155.52MHz, Integration Range: 12kHz – 20MHz		0.116		ps
tsk(o)	Output Skew; NOT	E 3, 5	Measured on the Rising Edge @ V _{DDO} /2			150	ps
	Part-to-Part Skew; NOTE 6	PCLK, nPCLK	<i>f</i> ≤ 150MHz			2.6	ns
		LVCMOS_CLK	<i>f</i> ≤ 150MHz			1.7	ns
tok(nn)	Part-to-Part Skew; NOTE 6	PCLK, nPCLK	<i>f</i> > 150MHz			2.2	ns
<i>t</i> sk(pp)		LVCMOS_CLK	<i>f</i> > 150MHz			1.7	ns
	Part-to-Part Skew; NOTE 4, 5	PCLK, nPCLK	Measured on the Rising Edge			1.2	ns
		LVCMOS_CLK	@ V _{DDO} /2			1	ns
t _R / t _F	Output Rise/Fall Time		20% to 80%	300		800	ps
odc	Output Duty Cycle		<i>f</i> ≤ 150MHz	43		57	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE: All parameters measured at 150MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output V_{DDO}/2.

NOTE 2: Measured from $V_{DD}/2$ to $V_{DDO}/2$.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DDO}/2.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltage, same temperature, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V_{DDO}/2.

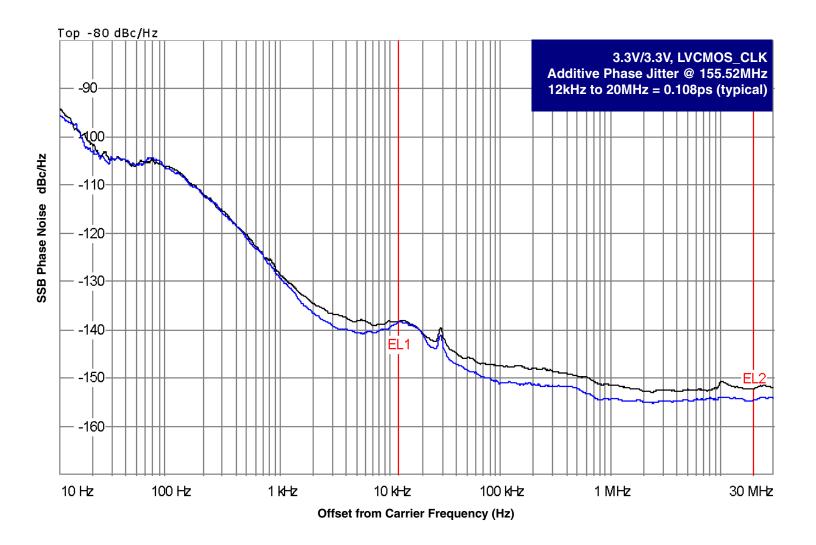
NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, same frequency and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDO}/2$.

Additive Phase Jitter

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio

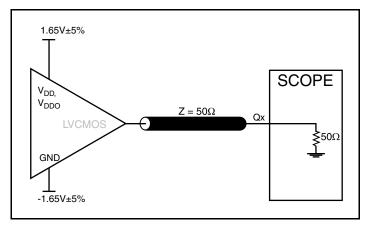
of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



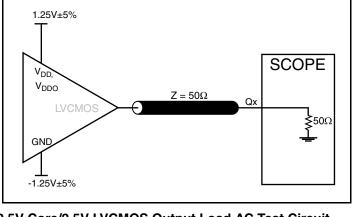
As with most timing specifications, phase noise measurements has issues relating to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.

The source generator, "SMA 100A 9kHz – 6GHz Low Noise Signal Generator as external input to an Agilent 8133A 3GHz Pulse Generator".

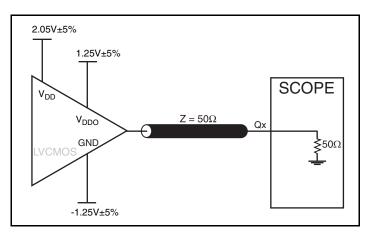
Parameter Measurement Information



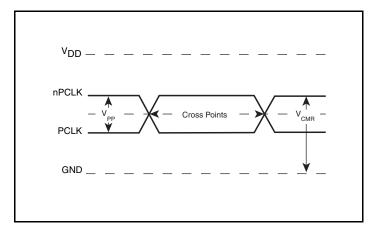
3.3V Core/3.3V LVCMOS Output Load AC Test Circuit



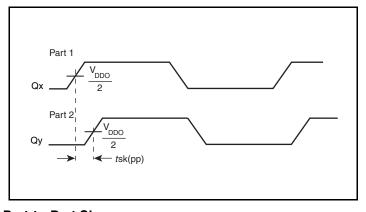
2.5V Core/2.5V LVCMOS Output Load AC Test Circuit



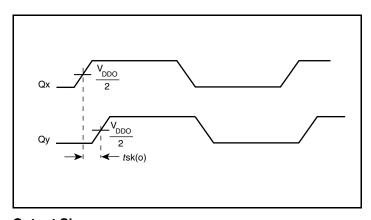
3.3V Core/2.5V LVCMOS Output Load AC Test Circuit



Differential Input Level

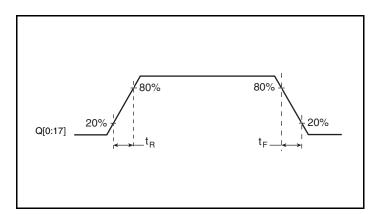


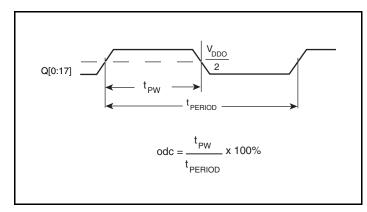
Part-to-Part Skew



Output Skew

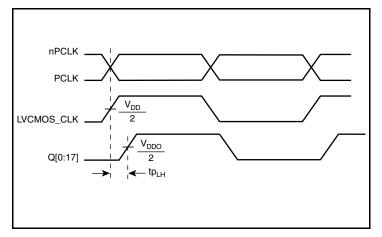
Parameter Measurement Information, continued





Output Rise/Fall Time

Output Duty Cycle/Pulse Width/Period



Propagation Delay

Applications Information

Wiring the Differential Input to Accept Single-Ended Levels

Figure 1 shows how a differential input can be wired to accept single ended levels. The reference voltage $V_{REF} = V_{CC}/2$ is generated by the bias resistors R1 and R2. The bypass capacitor (C1) is used to help filter noise on the DC bias. This bias circuit should be located as close to the input pin as possible. The ratio of R1 and R2 might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is 2.5V and $V_{CC} = 3.3V$, R1 and R2 value should be adjusted to set V_{REF} at 1.25V. The values below are for when both the single ended swing and V_{CC} are at the same voltage. This configuration requires that the sum of the output impedance of the driver (Ro) and the series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the input will attenuate the signal in half. This can be done in one of two ways. First, R3 and R4 in parallel should equal the transmission

line impedance. For most 50Ω applications, R3 and R4 can be 100Ω . The values of the resistors can be increased to reduce the loading for slower and weaker LVCMOS driver. When using single-ended signaling, the noise rejection benefits of differential signaling are reduced. Even though the differential input can handle full rail LVCMOS signaling, it is recommended that the amplitude be reduced. The datasheet specifies a lower differential amplitude, however this only applies to differential signals. For single-ended applications, the swing can be larger, however $V_{\rm IL}$ cannot be less than -0.3V and $V_{\rm IH}$ cannot be more than $V_{\rm CC}$ + 0.3V. Though some of the recommended components might not be used, the pads should be placed in the layout. They can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a differential signal.

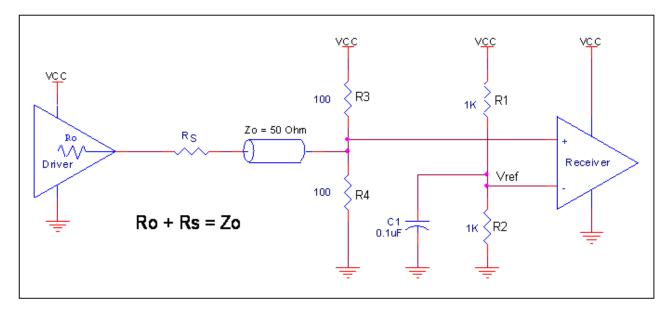


Figure 1. Recommended Schematic for Wiring a Differential Input to Accept Single-ended Levels

LVPECL Clock Input Interface

The PCLK /nPCLK accepts LVPECL, SSTL and other differential signals. Both differential signals must meet the V_{PP} and V_{CMR} input requirements. *Figures 2A to 2C* show interface examples for the PCLK/nPCLK input driven by the most common driver types. The

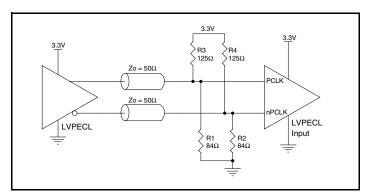


Figure 2A. PCLK/nPCLK Input Driven by a 3.3V LVPECL Driver

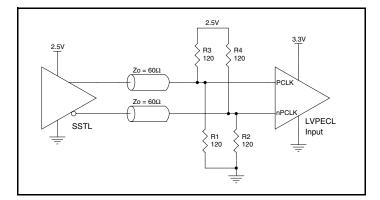


Figure 2C. PCLK/nPCLK Input Driven by an SSTL Driver

input interfaces suggested here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

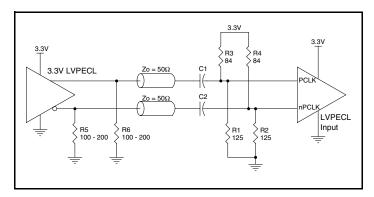


Figure 2B. PCLK/nPCLK Input Driven by a 3.3V LVPECL Driver with AC Couple

Recommendations for Unused Input and Output Pins

Inputs:

PCLK/nPCLK Inputs

For applications not requiring the use of the differential input, both PCLK and nPCLK can be left floating. Though not required, but for additional protection, a $1 \text{k}\Omega$ resistor can be tied from PCLK to ground.

LVCMOS_CLK Input

For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a $1 k\Omega$ resistor can be tied from the LVCMOS_CLK input to ground.

LVCMOS Control Pins

All control pins have internal pulldowns; additional resistance is not required but can be added for additional protection. A $1 \text{k}\Omega$ resistor can be used.

Outputs:

LVCMOS Outputs

All unused LVCMOS output can be left floating. There should be no trace attached.

Power Considerations

This section provides information on power dissipation and junction temperature for the ICS83940DI-01. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS83940DI-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{DD} = 3.3V + 5\% = 3.465V$, which gives worst case results.

• Power (core)_{MAX} = $V_{DD\ MAX}$ * ($I_{DD} + I_{DDO}$) = 3.465V *(26mA + 28mA) = **187.11mW**

Dynamic Power Dissipation at 175MHz

Power (175MHz) = C_{PD} * Frequency * $(V_{DD})^2$ * number of outputs = 9pF * 175MHz * $(3.465V)^2$ * 18 = **340.4mW**

Total Power Dissipation

- Total Power
 - = Power (core) $_{MAX}$ + Power (175MHz)
 - = 187.15 mW + 340.4 mW
 - = 527.5mW

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature, Tj, to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for Tj is as follows: Tj = θ_{JA} * Pd_total + T_A

Tj = Junction Temperature

 θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 53.5°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

 $85^{\circ}\text{C} + 0.528\text{W} * 53.5^{\circ}\text{C/W} = 113.2^{\circ}\text{C}$. This is well below the limit of 125°C .

This calculation is only an example. Tj will vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 6. Thermal Resistance θ_{JA} for 32 Lead LQFP, Forced Convection

θ_{JA} by Velocity					
Meters per Second	0	1	2.5		
Multi-Layer PCB, JEDEC Standard Test Boards	53.5°C/W	48.0°C/W	44.0°C/W		

Reliability Information

Table 7. θ_{JA} vs. Air Flow Table for a 32 Lead LQFP

θ_{JA} vs. Air Flow					
Meters per Second	0	1	2.5		
Multi-Layer PCB, JEDEC Standard Test Boards	53.5°C/W	48.0°C/W	44.0°C/W		

Transistor Count

The transistor count for ICS83940I-01 is: 819

Package Outline and Package Dimensions

Package Outline - Y Suffix for 32 Lead LQFP

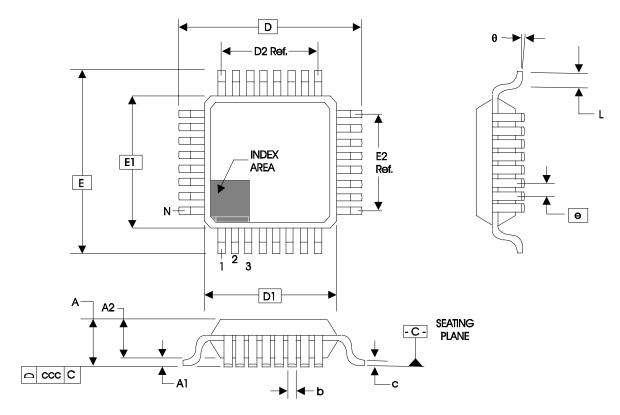


Table 8. Package Dimensions for 32 Lead LQFP

JEDEC Variation: ABC - HD All Dimensions in Millimeters							
Symbol	Minimum Nominal Maximum						
N	32						
Α			1.60				
A1	0.05 0.10 0.15						
A2	1.35 1.40 1.45						
b	0.30 0.37 0.45						
С	0.09		0.20				
D&E	9.00 Basic						
D1 & E1	7.00 Basic						
D2 & E2	5.60 Ref.						
е	0.80 Basic						
L	0.45 0.60 0.75						
θ	0° 7°						
ccc	0.10						

Reference Document: JEDEC Publication 95, MS-026

Ordering Information

Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
83940DYI-01	ICS83940DI01	32 Lead LQFP	Tray	-40°C to 85°C
83940DYI-01T	ICS83940DI01	32 Lead LQFP	1000 Tape & Reel	-40°C to 85°C
83940DYI-01LF	ICS83940DI01L	"Lead-Free" 32 Lead LQFP	Tray	-40°C to 85°C
83940DYI-01LFT	ICS83940DI01L	"Lead-Free" 32 Lead LQFP	1000 Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

While the information presented herein has been checked for both accuracy and reliability, Integrated Device Technology (IDT) assumes no responsibility for either its use or for the infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial and industrial applications. Any other applications, such as those requiring high reliability or other extraordinary environmental requirements are not recommended without additional processing by IDT. IDT reserves the right to change any circuitry or specifications without notice. IDT does not authorize or warrant any IDT product for use in life support devices or critical medical instruments.

We've Got Your Timing Solution



6024 Silver Creek Valley Road San Jose, California 95138 Sales

800-345-7015 (inside USA) +408-284-8200 (outside USA) Fax: 408-284-2775

www.IDT.com/go/contactIDT

Technical Support

netcom@idt.com +480-763-2056

DISCLAIMER Integrated Device Technology, Inc. (IDT) and its subsidiaries reserve the right to modify the products and/or specifications described herein at any time and at IDT's sole discretion. All information in this document, including descriptions of product features and performance, is subject to change without notice. Performance specifications and the operating parameters of the described products are determined in the independent state and are not guaranteed to perform the same way when installed in customer products. The information contained herein is provided without representation or warranty of any kind, whether express or implied, including, but not limited to, the suitability of IDT's products for any particular purpose, an implied warranty of merchantability, or non-infringement of the intellectual property rights of others. This document is presented only as a guide and does not convey any license under intellectual property rights of IDT or any third parties.

IDT's products are not intended for use in life support systems or similar devices where the failure or malfunction of an IDT product can be reasonably expected to significantly affect the health or safety of users. Anyone using an IDT product in such a manner does so at their own risk, absent an express, written agreement by IDT.

Integrated Device Technology, IDT and the IDT logo are registered trademarks of IDT. Other trademarks and service marks used herein, including protected names, logos and designs, are the property of IDT or their respective third party owners.

Copyright 2010. All rights reserved.